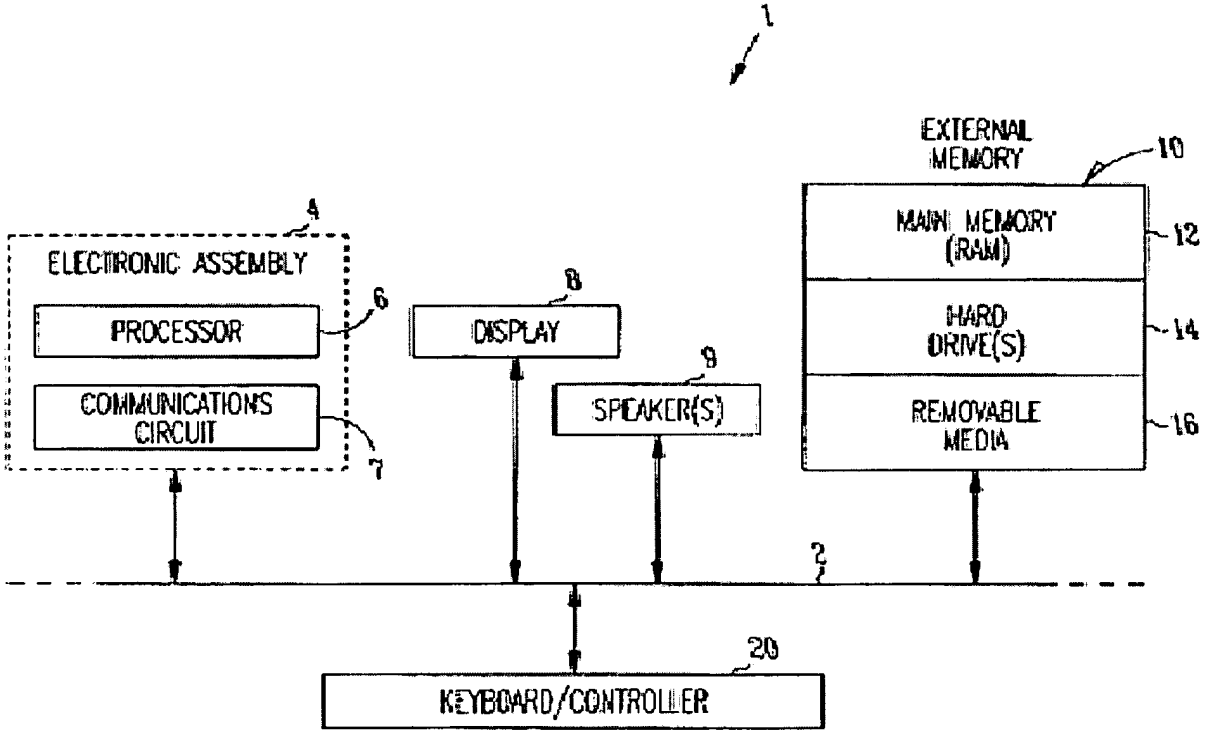
1
EXTERNAL MEMORY
10
4
ELECTRONIC ASSEMBLY
MAIN MEMORY (RAM)
12
8
PROCESSOR
6
DISPLAY
HARD DRIVE(S)
14
9
COMMUNICATIONS CIRCUIT
7
SPEAKER(S)
REMOVABLE MEDIA
16
2
20
KEYBOARD/CONTROLLER

Fig. 1

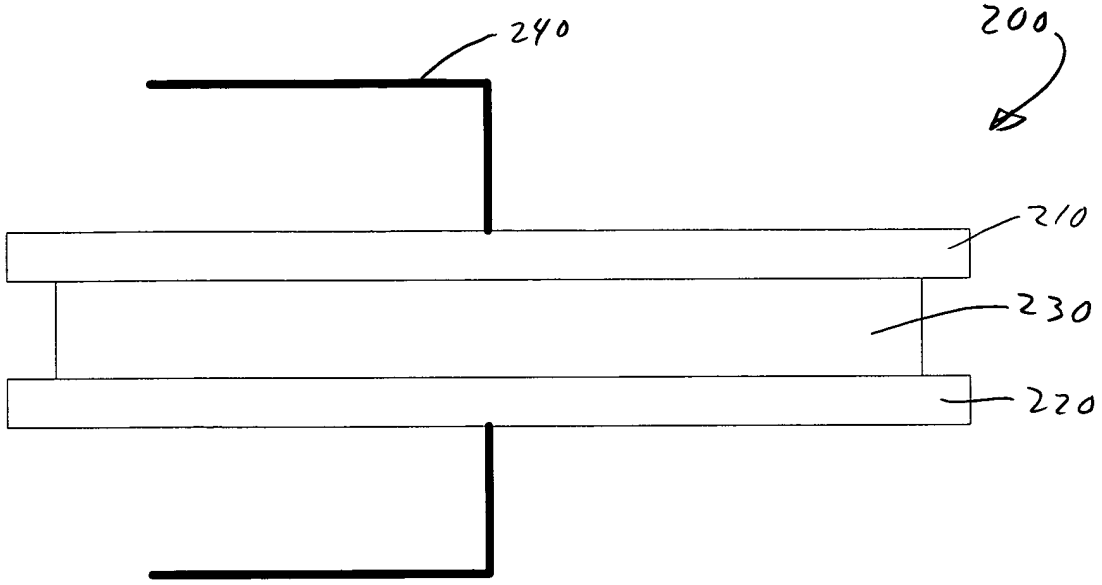

Fig. 2

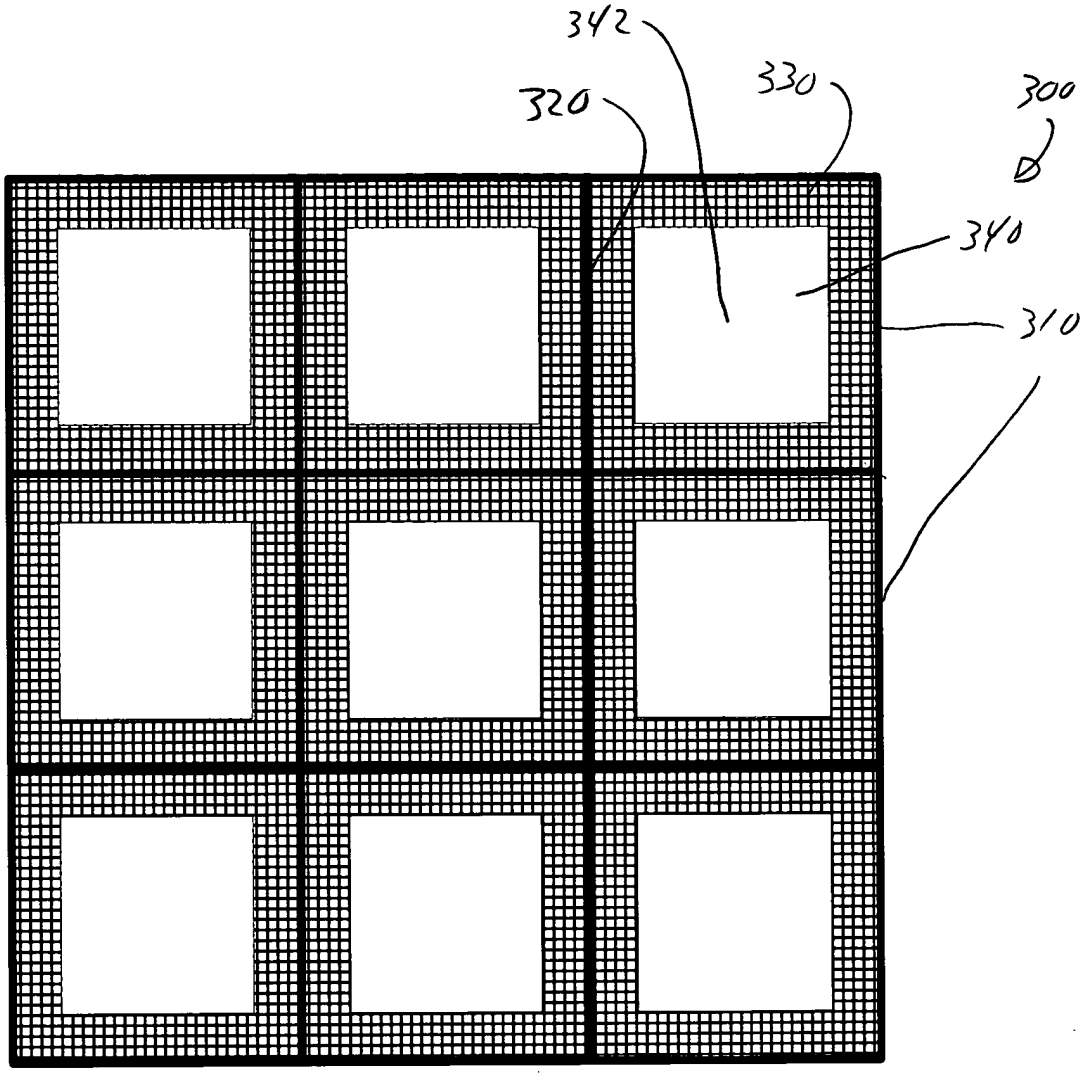

Fig. 3

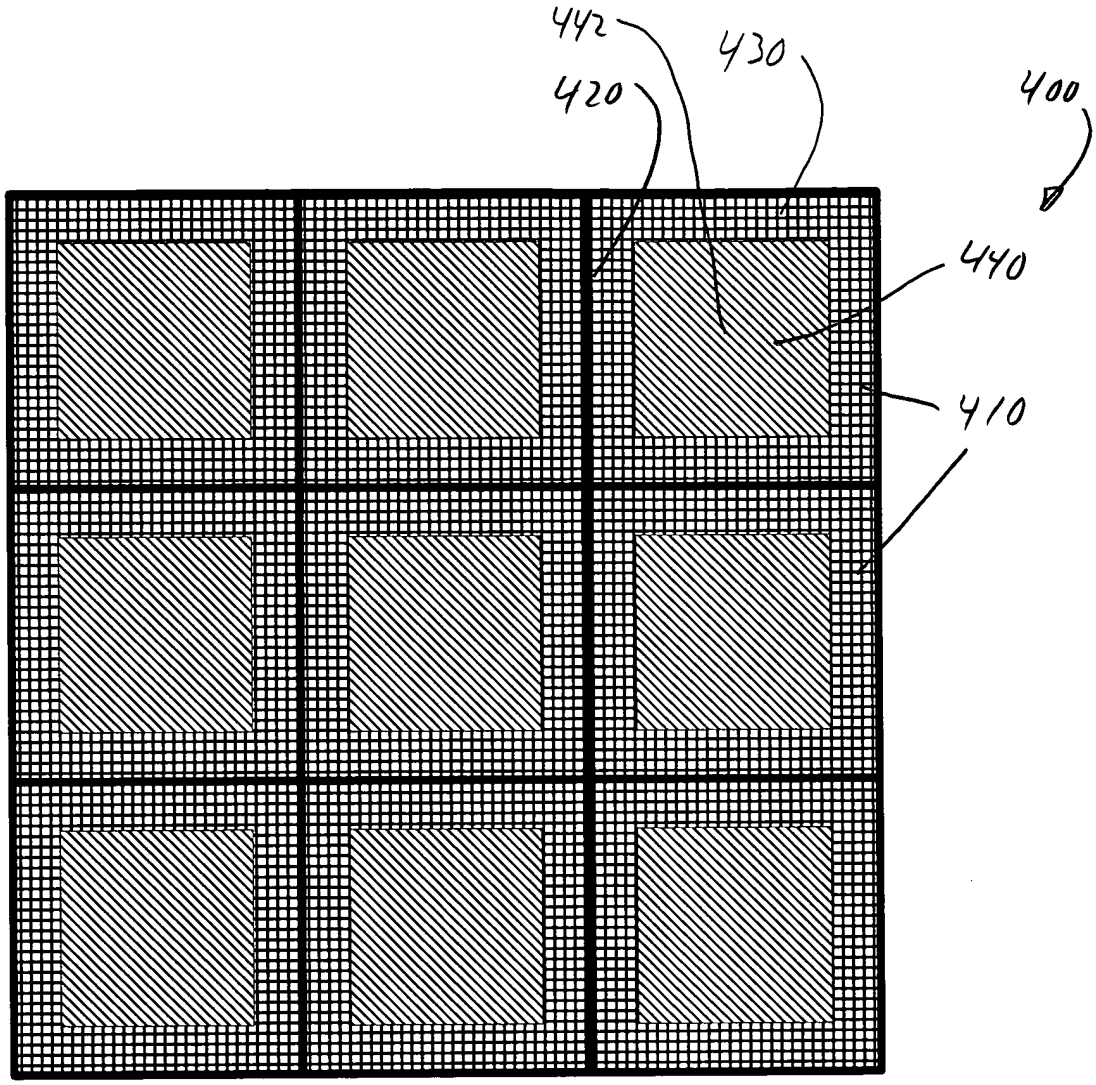

Fig. 4

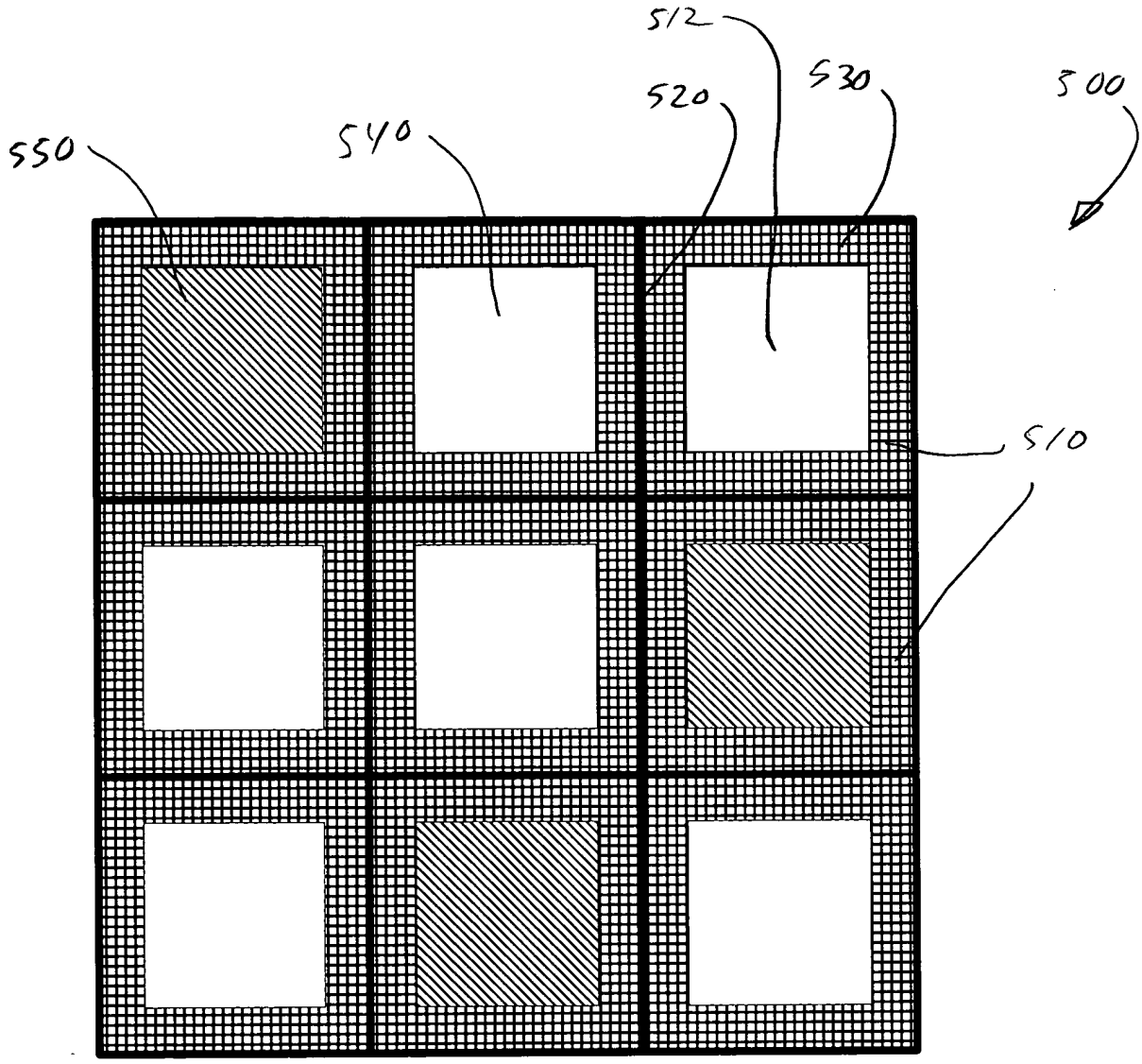

Fig. 5

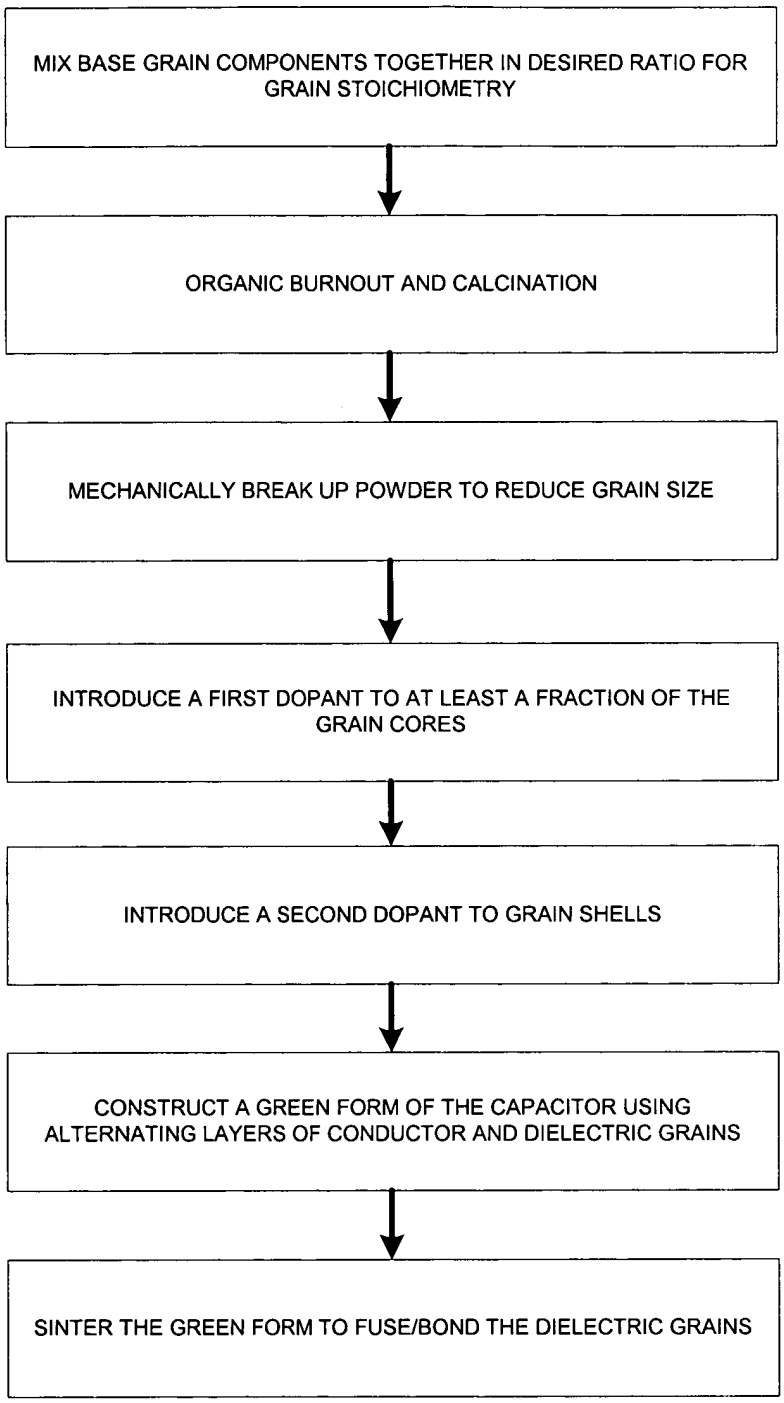
MIX BASE GRAIN COMPONENTS TOGETHER IN DESIRED RATIO FOR GRAIN STOICHIOMETRY
ORGANIC BURNOUT AND CALCINATION
MECHANICALLY BREAK UP POWDER TO REDUCE GRAIN SIZE
INTRODUCE A FIRST DOPANT TO AT LEAST A FRACTION OF THE GRAIN CORES
INTRODUCE A SECOND DOPANT TO GRAIN SHELLS
CONSTRUCT A GREEN FORM OF THE CAPACITOR USING ALTERNATING LAYERS OF CONDUCTOR AND DIELECTRIC GRAINS
SINTER THE GREEN FORM TO FUSE/BOND THE DIELECTRIC GRAINS

Fig. 6